

IEEE EPS as Moderator and Panelist in IPC Panel Discussion

25th July 2024



- IPC has organized a Panel Discussion at Penang on the Importance of Advanced Packaging Technology in Semiconductor & Electronics Industry, to support the 3rd Edition of Integrated Electronics Manufacturing & Interconnections 2024.
- IEEE Malaysia and EPS Committee Dr Bernard has been invited as Moderator, and IEEE EPS Chair Dr Eu Poh Leng (also representing NXP and MSIA) as Panelist, along with other speakers from Singapore, Phillipines, India, Australia, Egypt and Vietnam.
- > 100 participants from the industry took part in this meaningful event.